

The embodiments of the invention in which an exclusive property or privilege is claimed are defined as follows:

1. A method of forming a bump structure, said
5 method comprising:

(a) using a light to pass through a photomask to expose a photosensitive material layer deposited on the surface of a substrate, wherein said photomask comprising two major portions that are formed by mirror image with each other,
10 the widths of openings formed in said photomask being increased from a central portion to an edge portion, the spaces between two adjacent said openings being decreased from said central portion to said edge, and a diffraction situation being generated when said light passing through
15 said photomask;

(b) shifting said substrate with a distance to a direction perpendicular to a surface of said photomask;

(c) exposing said photosensitive material layer by using said photomask; and

20 (d) developing the photosensitive material to form said bump structure.

2. The method of claim 1, wherein said light is an UV light.

3. The method of claim 1, wherein the width of said openings is about $0.5 \mu\text{m}$ to $12 \mu\text{m}$.

4. The method of claim 1, wherein the said space
5 between two adjacent said openings is about $0.5 \mu\text{m}$ to $15 \mu\text{m}$.

10 5. The method of claim 1, wherein said distance may smooth said diffraction situation.

6. The method of claim 1, wherein said distance is about $0 \mu\text{m}$ to $\pm 10 \mu\text{m}$.

15 7. A method of forming a liquid crystal display, said method comprising:

providing a pair of light polarizers;

forming a compensator on one of said pair of light polarizers;

20 forming a pair of transparent insulating substrate on said compensator and on other one of said pair of light polarizers;

forming bump structures on at least one of said pair of transparent insulating substrate by following steps:

(a) using a light to pass through a photomask to expose a photosensitive material layer deposited on the surface of a substrate, wherein said photomask comprising two major portions that are formed by mirror image with each other, the widths of openings formed in said photomask being increased from a central portion to an edge portion, the spaces between two adjacent said openings being decreased from said central portion to said edge, and a diffraction situation being generated when said light passing through said photomask;

(b) shifting said substrate with a distance to a direction perpendicular to a surface of said photomask;

(c) exposing said photosensitive material layer by using said photomask; and

(d) developing the photosensitive material to form said bump structure.

forming orientation layers over said pair of transparent insulating substrate and over said bump structures; and providing liquid crystal molecules between said pair of transparent insulating substrate.

8. The method of claim 7, wherein said light is an UV light.

9. The method of claim 7, wherein the width of said openings is about $0.5 \mu\text{m}$ to $12 \mu\text{m}$.

5 10. The method of claim 7, wherein the said space between two adjacent said openings is about $0.5 \mu\text{m}$ to $15 \mu\text{m}$.

10 11. The method of claim 7, wherein said distance may smooth said diffraction situation.

12. The method of claim 7, wherein said distance is about $0 \mu\text{m}$ to $\pm 10 \mu\text{m}$.